

Microcomputer Components

8-Bit CMOS Microcontroller



Data Sheet 04.97

C501 Data Revision H		1997-04-01					
Previous R	eleases :	11.92, 11.93, 08.94, 08.95, 10.96					
Page (previous version)	Page (new version)	Subjects (changes since last revision)					
general		C501G-1E OTP version included					
4	4	Ordering information resorted and C501G-1E types added					
5	5	Table with literature hints added					
5-7	5-7	Pin configuration logic symbol for pins EA/Vpp and ALE/PROG updated					
11	11	Pin description for ALE/PROG and EA/Vpp completed					
8, 9, 10	8, 9, 10	Port 1, 3, 2 pin description: "bidirectional" replaced by "quasi- bidirectional"					
13	13	Block diagram updated for C501G-1E					
14	14	New design of register (PSW) description					
-	15	"Memory organization" added					
15-18	16-18	Actualized design of the SFR tables					
17	17	Reset value of T2CON corrected					
-	25-28	Description for the C501-1E OTP version added					
-	31	DC characteristics for C501-1E added					
41	41	Timing "External Clock Drive" now behind "Data Memory Cycle"					
-	43, 44	AC characteristics for C501-1E added					

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8-Bit CMOS Microcontroller

C501

Preliminary

- Fully compatible to standard 8051 microcontroller
- Versions for 12/24/40 MHz operating frequency
- Program memory : completely external (C501-L) 8K × 8 ROM (C501-1R) 8K × 8 OTP memory (C501-1E)
- 256 × 8 RAM
- Four 8-bit ports
- Three 16-bit timers / counters (timer 2 with up/down counter feature)
- USART
- Six interrupt sources, two priority levels
- Power saving modes
- Quick Pulse programming algorithm (C501-1E only)
- 2-Level program memory lock (C501-1E only)
- P-DIP-40, P-LCC-44, and P-MQFP-44 package
- Temperature ranges : SAB-C501 T_A : 0 °C to 70 °C SAF-C501 T_A : - 40 °C to 85 °C

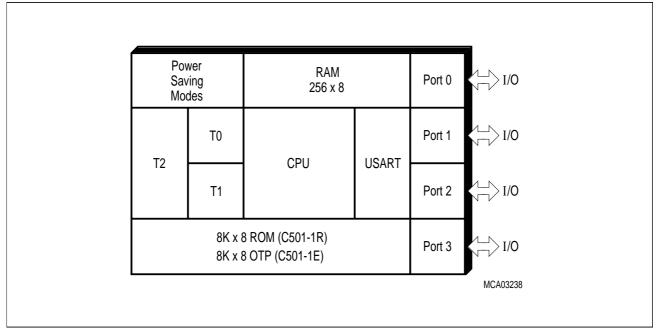


Figure 1 C501G Functional Units

The C501-1R contains a non-volatile $8K \times 8$ read-only program memory, a volatile 256×8 read/ write data memory, four ports, three 16-bit timers counters, a seven source, two priority level interrupt structure and a serial port. The C501-L is identical, except that it lacks the program memory on chip. The C501-1E contains a one-time programmable (OTP) program memory on chip. The term C501 refers to all versions within this specification unless otherwise noted. Further, the term C501 refers to all versions which are available in the different temperature ranges, marked with SAB-C501... or SAF-C501.....

Туре	Ordering Code	Package	Description (8-Bit CMOS microcontroller)
SAB-C501G-LN	Q67120-C969	P-LCC-44	for external memory (12 MHz)
SAB-C501G-LP	Q67120-C968	P-DIP-40	
SAB-C501G-LM	Q67127-C970	P-MQFP-44	
SAB-C501G-L24N	Q67120-C1001	P-LCC-44	for external memory (24 MHz)
SAB-C501G-L24P	Q67120-C999	P-DIP-40	
SAB-C501G-L24M	Q67127-C1014	P-MQFP-44	
SAB-C501G-L40N	Q67120-C1002	P-LCC-44	for external memory (40 MHz)
SAB-C501G-L40P	Q67120-C1000	P-DIP-40	
SAB-C501G-L40M	Q67127-C1009	P-MQFP-44	
SAF-C501G-L24N	Q67120-C1011	P-LCC-44	for external memory (24 MHz)
SAF-C501G-L24P	Q67120-C1010	P-MQFP-44	ext. temp. – 40 °C to 85 °C
SAB-C501G-1RN	Q67120-DXXX	P-LCC-44	with mask-programmable ROM (12 MHz)
SAB-C501G-1RP	Q67120-DXXX	P-DIP-40	
SAB-C501G-1RM	Q67127-DXXX	P-MQFP-44	
SAB-C501G-1R24N	Q67120-DXXX	P-LCC-44	with mask-programmable ROM (24 MHz)
SAB-C501G-1R24P	Q67120-DXXX	P-DIP-40	
SAB-C501G-1R24M	Q67127-DXXX	P-MQFP-44	
SAB-C501G-1R40N	Q67120-DXXX	P-LCC-44	with mask-programmable ROM (40 MHz)
SAB-C501G-1R40P	Q67120-DXXX	P-DIP-40	
SAB-C501G-1R40M	Q67127-DXXX	P-MQFP-44	
SAF-C501G-1R24N	Q67120-DXXX	P-LCC-44	with mask-programmable ROM (24 MHz) ext. temp. – 40 °C to 85 °C
SAF-C501G-1R24P	Q67120-DXXX	P-DIP-40	
SAB-C501G-1EN	Q67120-C1054	P-LCC-44	with OTP memory (12 MHz)
SAB-C501G-1EP	Q67120-C1056	P-DIP-40	
SAF-C501G-1EN	Q67120-C2002	P-LCC-44	with OTP memory (12 MHz))
SAF-C501G-1EP	Q67120-C2003	P-DIP-40	ext. temp. – 40 °C to 85 °C
SAB-C501G-1E24N	Q67120-C2005	P-LCC-44	with OTP memory (24 MHz)
SAB-C501G-1E24P	Q67120-C2006	P-DIP-40	
SAF-C501G-1E24N	Q67120-C2008	P-LCC-44	with OTP memory (24 MHz))
SAF-C501G-1E24P	Q67120-C2009	P-DIP-40	ext. temp. – 40 °C to 85 °C

Ordering Information

Note: Versions for extended temperature range – 40 °C to 110 °C (SAH-C501G) on request. The ordering number of ROM types (DXXX extensions) is defined after program release (verification) of the customer.

Additional Literature

For further information about the C501 the following literature is available :

Title	Ordering Number
C501 8-Bit CMOS Microcontroller User's Manual	B158-H6723-X-X-7600
C500 Microcontroller Family Architecture and Instruction Set User's Manual	B158-H6987-X-X-7600
C500 Microcontroller Family - Pocket Guide	B158-H6986-X-X-7600

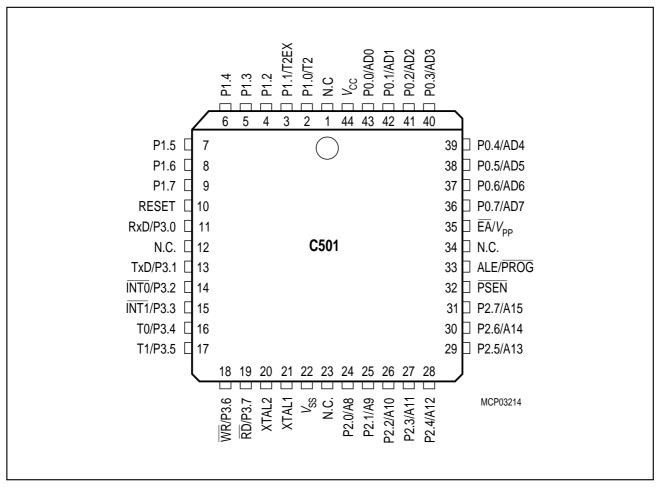
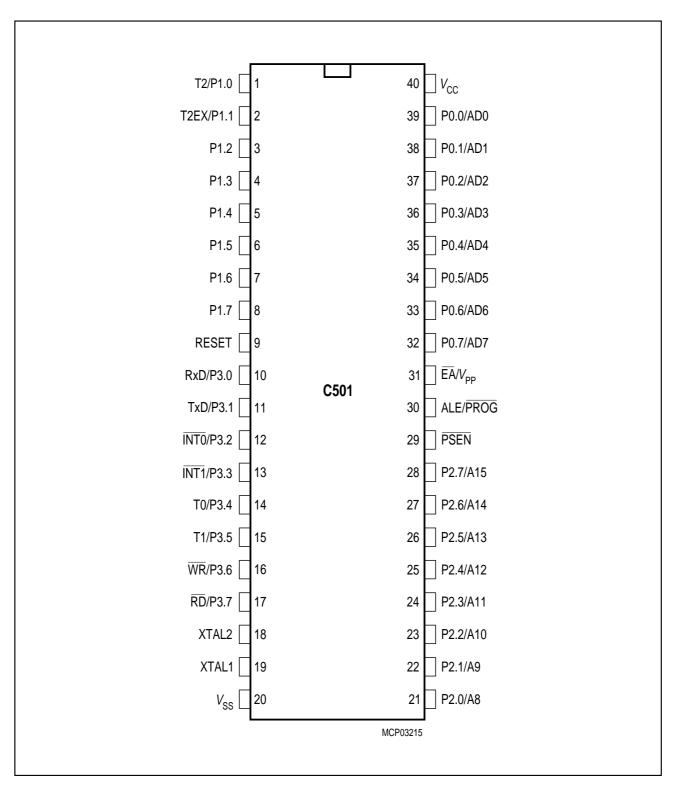


Figure 2 Pin Configuration P-LCC-44 Package (Top view)

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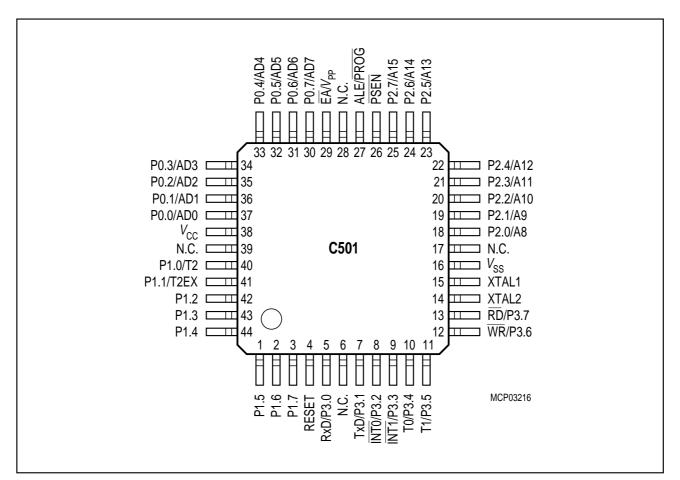


Figure 4 Pin Configuration P-MQFP-44 Package (top view)

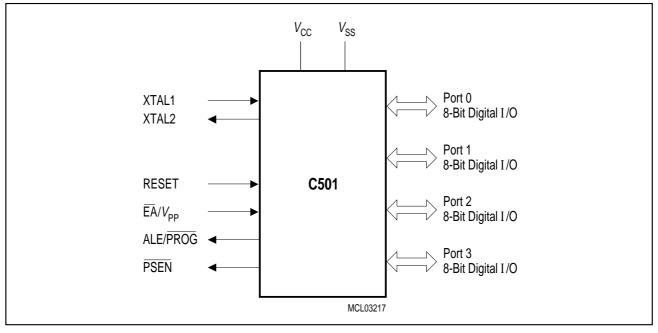


Figure 5 Logic Symbol

Table 1 **Pin Definitions and Functions**

Symbol		Pin Numb	er	I/O*)	Function		
	P-LCC-44	P-DIP-40	P-MQFP-44				
P1.0 – P1.7	2–9 2 3	1–8 1 2	40-44, 1-3, 40 41	I/O	Port 1 is a quasi-bidirectional I/O port with internal pull-up resistors. Port 1 pins that have 1s written to them are pulled high by the internal pullup resistors, and in that state can be used as inputs. As inputs, port 1 pins being externally pulled low will source current (I_{IL} , in the DC character- istics) because of the internal pull-up resistors. Port 1 also contains the timer 2 pins as secondary function. The output latch corresponding to a secondary function must be pro-grammed to a one (1) for that function to operate. The secondary functions are assigned to the pins of port 1, as follows: P1.0 T2 Input to counter 2 P1.1 T2EX Capture - Reload trigger of timer 2 / Up-Down count		

*) I = Input O = Output

Table 1 Pin Definitions and Functions (cont'd)

Symbol P3.0 – P3.7	Pin Number				Function			
	P-LCC-44	P-DIP-40	P-MQFP-44					
	11, 13–19 11	10-17	5, 7–13	Ι/Ο	intern have the in state inputs low w chara pull-u intern wemo variou corres must function The s the pi	uasi-bic al pull-u 1s writte ternal p they ca s, port 3 ill sourc cteristic p resist upt, time ory stro us optio spondin be prog on to op econda	ary functions are assigned to ort 3, as follows: receiver data input (asyn-	
	13	11	7		P3.1	P3.1 T×D transmitter da (asynchronou output (synch	output (synchronous) of serial interface 0 transmitter data output (asynchronous) or clock output (synchronous) of the serial interface 0	
	14	12	8		P3.2	INT0	interrupt 0 input/timer 0 gate control	
	15	13	9		P3.3	INT1	interrupt 1 input/timer 1 gate control	
	16 17 18 19	14 15 16 17	10 11 12 13		P3.4 P3.5 P3.6 P3.7	T0 T1 WR	counter 0 input counter 1 input the write control signal lat- ches the data byte from port 0 into the external data memory the read control signal enables the external data	

Table 1

Pin Definitions and Functions (cont'd)

Symbol		Pin Numb	er	I/O*)	Function		
	P-LCC-44 P-DIP-40		P-MQFP-44				
XTAL2	20	18	14	-	XTAL2 Output of the inverting oscillator amplifier.		
XTAL1	21 19 15			-	XTAL1 Input to the inverting oscillator amplifier and input to the internal clock generator circuits. To drive the device from an external clock source, XTAL1 should be driven, while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is divided down by a divide-by-two flip-flop. Minimum and maximum high and low times as well as rise fall times specified in the AC characteristics must be observed.		
P2.0 – P2.7	24–31	21–28	8 18–25 I/O Port 2 is a q intern have by the that s inputs low w chara pull-u order extern acces use 1 In this pull-u acces use 8		Port 2 is a quasi-bidirectional I/O port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state they can be used as inputs. As inputs, port 2 pins being externally pulled low will source current (I_{IL} , in the DC characteristics) because of the internal pull-up resistors. Port 2 emits the high- order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application it uses strong internal pull-up resistors when issuing 1s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), port 2 issues the contents of the P2 special function register.		

Table 1 Pin Definitions and Functions (cont'd)

Symbol		Pin Numb	er	I/O*)	Function		
	P-LCC-44 P-DIP-40		P-MQFP-44				
PSEN	32	29	26	0	The Program Store Enable output is a control signal that enables the external program memory to the bus during external fetch operations. It is activated every six oscillator periods except during external data memory accesses. Remains high during internal program execution.		
RESET	10	9	4	I	RESET A high level on this pin for two machine cycles while the oscillator is running resets the device. An internal diffused resistor to $V_{\rm SS}$ permits power-on reset using only an external capacitor to $V_{\rm CC}$.		
ALE/PROG	33	30	27	I/O	The Address Latch Enable output is used for latching the low-byte of the address into external memory during normal operation. It is activated every six oscillator periods except during an external data memory access. For the C501-1E this pin is also the program pulse input (PROG) during OTP memory programming.		
ĒĀ/V _{PP}	35	31	29	I	External Access Enable When held at high level, instructions are fetched from the internal ROM (C501-1R and C501-1E) when the PC is less than 2000_{H} . When held at low level, the C501 fetches all instructions from external program memory. For the C501-L this pin must be tied low. This pin also receives the programming supply voltage V_{PP} during OTP memory programming (C501-1E) only).		

*) I = Input O = Output

Symbol		Pin Numb	er	I/O*)	Function		
	P-LCC-44	P-DIP-40	P-MQFP-44				
P0.0 – P0.7	43–36	39–32	37–30	I/O	Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program or data memory. In this application it uses strong internal pull-up resistors when issuing 1s. Port 0 also outputs the code bytes during program verification in the C501-1R and C501-1E. External pull-up resistors are required during program verification.		
V _{SS}	22	20	16	-	Circuit ground potential		
V _{cc}	44	40	38	-	Supply terminal for all operating modes		
N.C.	1, 12, 23, 34	_	6, 17, 28, 39	-	No connection		

*) I = Input O = Output

Functional Description

The C501 is fully compatible to the standard 8051 microcontroller family.

It is compatible with the 80C32/52/82C52. While maintaining all architectural and operational characteristics of the 8051microcontroller family, the C501 incorporates some enhancements in the timer 2 unit.

Figure 6 shows a block diagram of the C501.

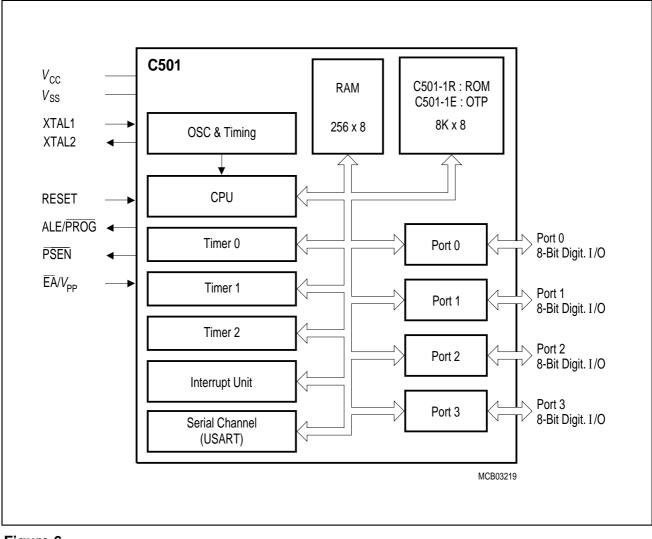


Figure 6 Block Diagram of the C501

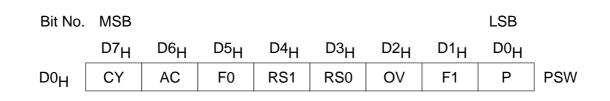
C501

CPU

The C501 is efficient both as a controller and as an arithmetic processor. It has extensive facilities for binary and BCD arithmetic and excels in its bit-handling capabilities. Efficient use of program memory results from an instruction set consisting of 44 % one-byte, 41 % two-byte, and 15% three-byte instructions. With a 12 MHz crystal, 58% of the instructions are executed in 1.0 μ s 24 MHz: 500 ns, 40 MHz : 300 ns).

Special Function Register PSW (Address D0_H)

Reset Value : 00H



Bit	Functior	Function							
СҮ		Carry Flag Used by arithmetic instruction.							
AC		Carry Flag	s which execute BCD operations.						
F0	General	Purpose Fl	lag						
RS1 RS0	-		ct control bits I to select one of the four register banks.						
	RS1	RS0	Function						
	0	0	Bank 0 selected, data address 00 _H -07 _H						
	0	1	Bank 1 selected, data address 08 _H -0F _H						
	1	0	Bank 2 selected, data address 10 _H -17 _H						
	1	1	Bank 3 selected, data address 18 _H -1F _H						
OV	Overflow Used by	0	instruction.						
F1	General	Purpose Fl	ag						
P	Set/clear	Parity Flag Set/cleared by hardware after each instruction to indicate an odd/even number of "one" bits in the accumulator, i.e. even parity.							

Memory Organization

The C501 CPU manipulates data and operands in the following four address spaces:

- up to 64 Kbyte of internal/external program memory
- up to 64 Kbyte of external data memory
- 256 bytes of internal data memory
- a 128 byte special function register area

Figure 7 illustrates the memory address spaces of the C501.

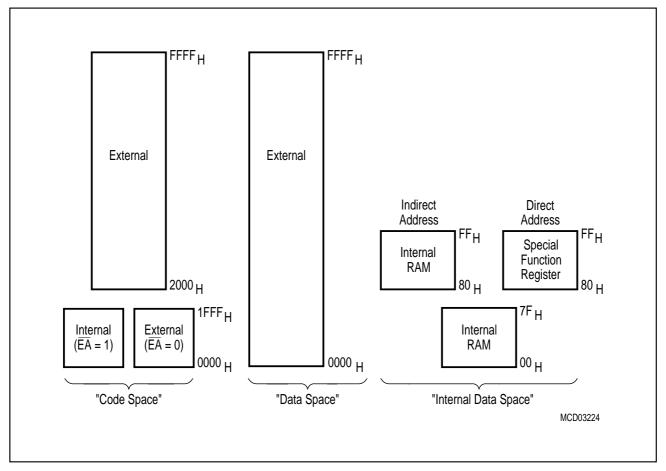


Figure 7 C501 Memory Map

C501

Special Function Registers

The registers, except the program counter and the four general purpose register banks, reside in the special function register area.

The 27 special function registers (SFRs) include pointers and registers that provide an interface between the CPU and the other on-chip peripherals. All SFRs with addresses where address bits 0-2 are 0 (e.g. 80_H , 88_H , 90_H , 98_H , ..., $F8_H$, FF_H) are bitaddressable.

The SFRs of the C501 are listed in **table 2** and **table 3**. In **table 2** they are organized in groups which refer to the functional blocks of the C501. **Table 3** illustrates the contents of the SFRs in numeric order of their addresses.

Table 2 **Special Function Registers - Functional Blocks**

Block	Symbol	Name	Address	Contents after Reset
CPU	ACC B DPH DPL PSW SP	Accumulator B-Register Data Pointer, High Byte Data Pointer, Low Byte Program Status Word Register Stack Pointer	E0_H ¹⁾ F0_H ¹⁾ 83 _H 82 _H D0_H ¹⁾ 81 _H	00 _H 00 _H 00 _H 00 _H 00 _H 07 _H
Interrupt System	IE IP	Interrupt Enable Register Interrupt Priority Register	A8 _H ¹⁾ B8 _H ¹⁾	0X000000B ³⁾ XX000000B ³⁾
Ports	P0 P1 P2 P3	Port 0 Port 1 Port 2 Port 3	80 _H ¹⁾ 90 _H ¹⁾ A0 _H ¹⁾ B0 _H ¹⁾	FF _H FF _H FF _H FF _H
Serial Channel	PCON ²⁾ SBUF SCON	Power Control Register Serial Channel Buffer Register Serial Channel Control Register	87 _H 99 _H 98 _H 1)	0XXX0000 _B ³⁾ XX _H ³⁾ 00 _H
Timer 0 / Timer 1	TCON TH0 TH1 TL0 TL1 TMOD	Timer 0/1 Control Register Timer 0, High Byte Timer 1, High Byte Timer 0, Low Byte Timer 1, Low Byte Timer Mode Register	88 _H ¹⁾ 8C _H 8D _H 8A _H 8B _H 89 _H	00 _H 00 _H 00 _H 00 _H 00 _H
Timer 2	T2CON T2MOD RC2H RC2L TH2 TL2	Timer 2 Control Register Timer 2 Mode Register Timer 2 Reload/Capture Register, High Byte Timer 2 Reload/Capture Register, Low Byt Timer 2 High Byte Timer 2 Low Byte	С8 _Н ¹⁾ С9 _Н СВ _Н СА _Н СО _Н СС _Н	00 _H XXXXXX0 _B ³⁾ 00 _H 00 _H 00 _H
Pow. Sav. Modes	PCON ²⁾	Power Control Register	87 _H	0XXX0000 _B ³⁾

Bit-addressable special function registers
 This special function register is listed repeatedly since some bits of it also belong to other functional blocks.
 "X" means that the value is undefined and the location is reserved

Table 3

Contents of the SFRs, SFRs in numeric order of their addresses

Addr	Register	Content after Reset ¹⁾	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
80 _H ²)	P0	FF _H	.7	.6	.5	.4	.3	.2	.1	.0
81 _H	SP	07 _H	.7	.6	.5	.4	.3	.2	.1	.0
82 _H	DPL	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
83 _H	DPH	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
87 _H	PCON	0XXX- 0000 _B	SMOD	-	-	-	GF1	GF0	PDE	IDLE
88 _H ²)	TCON	00 _H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0
89 _H	TMOD	00 _H	GATE	C/T	M1	MO	GATE	C/T	M1	MO
8A _H	TL0	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
8BH	TL1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
8CH	TH0	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
8D _H	TH1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
90 _H ²)	P1	FF _H	.7	.6	.5	.4	.3	.2	.1	.0
98 _H ²)	SCON	00 _H	SM0	SM1	SM2	REN	TB8	RB8	ТІ	RI
99H	SBUF	хх _Н	.7	.6	.5	.4	.3	.2	.1	.0
А0 _Н ²)	P2	FF _H	.7	.6	.5	.4	.3	.2	.1	.0
А8 _Н ²)	IE	0X00- 0000 _B	EA	-	ET2	ES	ET1	EX1	ET0	EX0
80 _H ²)	P3	FF _H	RD	WR	T1	ТО	INT1	INT0	TxD	RxD
88 _H ²)	IP	XX00. 0000 _B	-	-	PT2	PS	PT1	PX1	PT0	PX0
C8 _H ²)	T2CON	00 _H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	$C/\overline{T2}$	CP/RL2
C9H	T2MOD	xxxx- xxx0 _B	-	-	-	_	-	-	-	DCEN
CAH	RC2L	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
СВН	RC2H	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
сс ^н	TL2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
CDH	TH2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
D0 _H ²⁾	PSW	00 _H	CY	AC	F0	RS1	RS0	OV	F1	Р
E0 _H ²)	ACC	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
F0 _H ²⁾	В	00 _H	.7	.6	.5	.4	.3	.2	.1	.0

X means that the value is undefined and the location is reserved
 Bit-addressable special function registers

Timer / Counter 0 and 1

Timer/counter 0 and 1 can be used in four operating modes as listed in table 4.

Table 4

Timer/Counter 0 and 1 Operating Modes

Mode	Description		ТМ	OD		Input Clock		
		Gate	C/T	M1	MO	internal	external (max)	
0	8-bit timer/counter with a divide-by-32 prescaler	Х	Х	0	0	$f_{OSC}/_{12 \times 32}$	fosc/24×32	
1	16-bit timer/counter	Х	Х	1	1	$f_{\rm OSC}/_{12}$	fosc/24	
2	8-bit timer/counter with 8-bit autoreload	Х	Х	0	0	f _{osc} / ₁₂	fosc/24	
3	Timer/counter 0 used as one 8-bit timer/counter and one 8-bit timer Timer 1 stops	X	Х	1	1	fosc/12	fosc/24	

In the "timer" function (C/ \overline{T} = '0') the register is incremented every machine cycle. Therefore the count rate is $f_{OSC}/12$.

In the "counter" function the register is incremented in response to a 1-to-0 transition at its corresponding external input pin (P3.4/T0, P3.5/T1). Since it takes two machine cycles to detect a falling edge the max. count rate is $f_{OSC}/24$. External inputs INTO and INT1 (P3.2, P3.3) can be programmed to function as a gate to facilitate pulse width measurements. **Figure 8** illustrates the input clock logic.

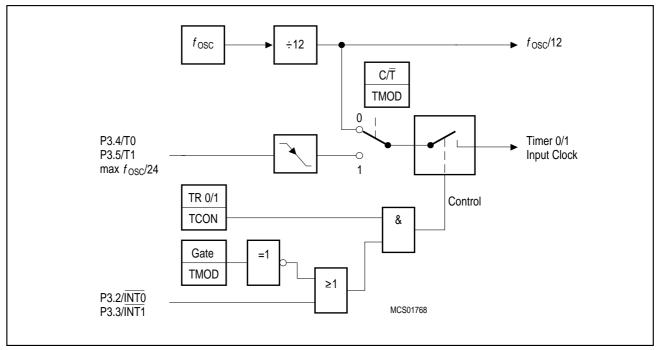


Figure 8 Timer/Counter 0 and 1 Input Clock Logic

Timer 2

Timer 2 is a 16-bit timer/counter with an up/down count feature. It can operate either as timer or as an event counter which is selected by bit $C/\overline{T2}$ (T2CON.1). It has three operating modes as shown in **table 5**.

Table 5

Timer/Counter 2 Operating Modes

	T2CON		T2MOD	T2CON			Input	Clock	
Mode	R×CLK or T×CLK	CP/ RL2	TR2	DCEN	EXEN	P1.1/ T2EX	Remarks	internal	external (P1.0/T2)
16-bit Auto-	0	0	1	0	0	Х	reload upon overflow		
reload	0	0	1	0	1	\downarrow	reload trigger (falling edge)	<i>f</i> _{OSC} /12	max f _{osc} /24
	0	0	1	1	X	0	Down counting		
	0	0	1	1	X	1	Up counting		
16-bit Cap- ture	0	1	1	x x	0	X ↓	16 bit Timer/ Counter (only up-counting) capture TH2,	f _{osc} /12	max f _{osc} /24
							$\begin{array}{l} TL2 \rightarrow RC2H, \\ RC2L \end{array}$		
Baud Rate Gene-	1	Х	1	Х	0	×	no overflow interrupt request (TF2)	f _{osc} /2	max
rator	1	Х	1	Х	1	\downarrow	extra external interrupt ("Timer 2")	J OSC -	f _{osc} /24
off	Х	Х	0	Х	Х	Х	Timer 2 stops	_	_

Note: $\downarrow = \neg$ falling edge

Serial Interface (USART)

The serial port is full duplex and can operate in four modes (one synchronous mode, three asynchronous modes) as illustrated in **table 6**. The possible baudrates can be calculated using the formulas given in **table 7**.

Table 6 USART Operating Modes

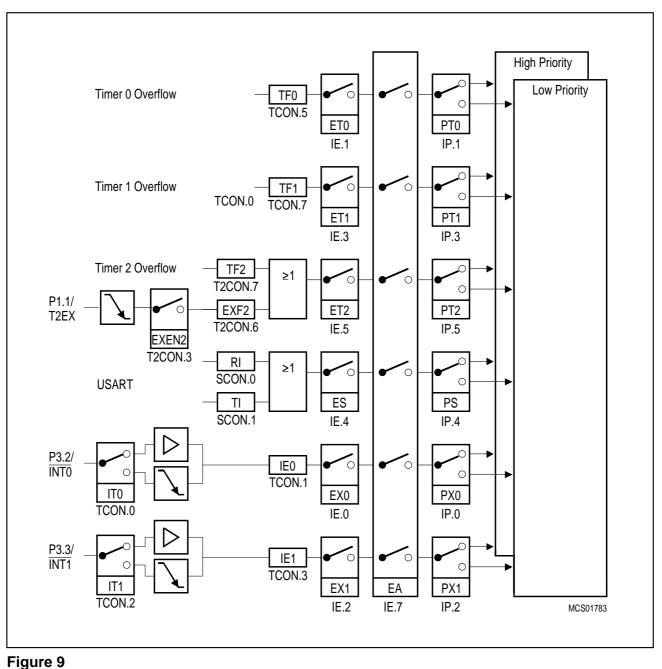
Mada	SCON		Baudrate	Description		
Mode	SM0	SM1				
0	0	0	<i>f</i> _{osc} /12	Serial data enters and exits through R×D. T×D outputs the shift clock. 8-bit are transmitted/received (LSB first)		
1	0	1	Timer 1/2 overflow rate	8-bit UART 10 bits are transmitted (through T×D) or received (R×D)		
2	1	0	$f_{\rm OSC}/32$ or $f_{\rm OSC}/64$	9-bit UART 11 bits are transmitted (T×D) or received (R×D)		
3	1	1	Timer 1/2 overflow rate	9-bit UART Like mode 2 except the variable baud rate		

Table 7Formulas for Calculating Baudrates

Baud Rate derived from	Interface Mode	Baudrate
Oscillator	0 2	$f_{ m OSC}$ /12 (2 ^{SMOD} $ imes f_{ m OSC}$) / 64
Timer 1 (16-bit timer) (8-bit timer with 8-bit autoreload)	1,3 1,3	$\begin{array}{c} (2^{\text{SMOD}} \times \text{timer 1 overflow rate}) / 32 \\ (2^{\text{SMOD}} \times f_{\text{OSC}}) / (32 \times 12 \times (256\text{-TH1})) \end{array}$
Timer 2	1,3	$f_{\rm OSC}$ / (32 × (65536-(RC2H, RC2L))

Interrupt System

The C501 provides 6 interrupt sources with two priority levels. **Figure 9** gives a general overview of the interrupt sources and illustrates the request and control flags.



Interrupt Request Sources

Table 8Interrupt Sources and their Corresponding Interrupt Vectors

Source (Request Flags)	Vector	Vector Address
IEO	External interrupt 0	0003 _H
TF0	Timer 0 interrupt	000B _H
IE1	External interrupt 1	0013 _H
TF1	Timer 1 interrupt	001B _H
RI + TI	Serial port interrupt	0023 _H
TF2 + EXF2	Timer 2 interrupt	002BH

A low-priority interrupt can itself be interrupted by a high-priority interrupt, but not by another lowpriority interrupt. A high-priority interrupt cannot be interrupted by any other interrupt source.

If two requests of different priority level are received simultaneously, the request of higher priority is serviced. If requests of the same priority are received simultaneously, an internal polling sequence determines which request is serviced. Thus within each priority level there is a second priority structure determined by the polling sequence as shown in **table 9**.

Table 9Interrupt Priority-Within-Level

Interrupt S	Priority	
External Interrupt 0,	IE0	High
Timer 0 Interrupt,	TF0	
External Interrupt 1,	IE1	\downarrow
Timer 1 Interrupt,	TF1	
Serial Channel,	RI + TI	
Timer 2 Interrupt,	TF2 + EXF2	Low

Power Saving Modes

Two power down modes are available, the Idle Mode and Power Down Mode.

The bits PDE and IDLE of the register PCON select the Power Down mode or the Idle mode, respectively. If the Power Down mode and the Idle mode are set at the same time, the Power Down mode takes precedence. **Table 10** gives a general overview of the power saving modes.

Table 10Power Saving Modes Overview

Mode	Entering Instruction Example	Leaving by	Remarks
Idle mode	ORL PCON, #01H	 – enabled interrupt – Hardware Reset 	CPU is gated off CPU status registers maintain their data. Peripherals are active
Power-Down Mode	ORL PCON, #02H	Hardware Reset	Oscillator is stopped, contents of on-chip RAM and SFR's are maintained (leaving Power Down Mode means redefinition of SFR contents).

In the Power Down mode of operation, V_{CC} can be reduced to minimize power consumption. It must be ensured, however, that V_{CC} is not reduced before the Power Down mode is invoked, and that V_{CC} is restored to its normal operating level, before the Power Down mode is terminated. The reset signal that terminates the Power Down mode also restarts the oscillator. The reset should not be activated before V_{CC} is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize (similar to power-on reset).

OTP Operation

The C501-1E is programmed by usng a modified Quick-Pulse Programming^{TM 1)} algorithm. It differs from older methods in the value used for V_{PP} (programming supply voltage) and in the width and number of the ALE/PROG pulses. The C501-1E contains two signature bytes that can be read and used by a programming system to identify the device. The signature bytes identify the manufacturer of the device.

Table 11 shows the logic levels for reading the signature byte, and for programming the program memory, the encryption table, and the security bits. The circuit configuration and waveforms for quick-pulse programming are shown in **figures 10** to **12**.

Table 11OTP Programming Modes

Mode	RESET	PSEN	ALE/ PROG	EA/V _{PP}	P2.7	P2.6	P3.7	P3.6
Read signature	1	0	1	1	0	0	0	0
Program code data	1	0	0	V _{PP}	1	0	1	1
Verify code data	1	0	1	1	0	0	1	1
Progam encryption table	1	0	0	V _{PP}	1	0	1	0
Program security bit 1	1	0	0	V _{PP}	1	1	1	1
Program security bit 2	1	0	0	V _{PP}	1	1	0	0

Notes :

1. "0" = valid low for that pin, "1" = valid high for that pin.

2. $V_{PP} = 12.75 \text{ V} \pm 0.25 \text{V}$

3. V_{CC} = 5 V \pm 10% during programming and verification.

4. ALE/PROG receives 25 programming pulses while V_{PP} is held at 12.75 V. Each programming pulse is low for 100 μ s (± 10 μ s) and high for a minimum of 10 μ s.

 $^{^{1)}\,}$ Quick-Pulse Programming TM is a trademark phrase of Intel Corporation

Quick-Pulse Programming

The setup for microcontroller quick-pulse programming is shown in **figure 10**. Note that the C501-1E is running with a 4 to 6 MHz oscillator The reason the oscillator needs to be running is that the device is executing internal address and program data transfers.

The address of the OTP memory location to be programmed is applied to port 1 and 2 as shown in **figure 10**. The code byte to be programmed into that location is applied to port 0. RESET, $\overrightarrow{\text{PSEN}}$ and pins of port 2 and 3 specified in **table 11** are held at the "Program code data" levels. The ALE/ $\overrightarrow{\text{PROG}}$ signal is pulsed low 25 times as shown in **figure 11**.

For programming of the encryption table, the 25 pulse programming sequence must be repeated for addresses 0 through $1F_H$, using the "Program encrytion table" levels. After the encryption table is programmed, verification cycles will produce only encrypted data.

For programming of the security bits, the 25 pulse programming sequence must be repeat using the "Program security bit" levels. After one security bit is programmed, further programming of the code memory and encryption table is disabled. However, the other security bit can still be programmed.

Note that the \overline{EA}/V_{PP} pin must not be allowed to go above the maximum specified V_{PP} level. for any amount of time. Even a narrow glitch above that voltage can cause permanent damage to the device. The V_{PP} source should be well regulated and free of glitches and overshoots.

Program Verification

If security bit 2 has not been programmed, the on-chip OTP program memory can be read out for program verification. The address of the OTP program memory locations to be read is applied to ports 1 and 2 as shown in **figure 12**. The other pins are held at the "Verify code data" levels indicated in **table 11**. The contents of the address location will be emitted on port 0. External pullups are required on port 0 for this operation.

If the encryption table has been programmed, the data presented at port 0 will be the exclusive NOR of the program byte with one of the encryption bytes. The user will have to know the encryption table contents in order to correctly decode the verification data. The encryption table itself cannot be read out.

Reading the SIgnature Bytes

The signature bytes are read by the same procedure as a normal verification of loctions 30_H and 31_H , except that P3.6 and P3.7 need to be pulled to a logic low. The values are :

 $30_{\text{H}} = E0_{\text{H}}$ indicates manufacturer $31_{\text{H}} = 71_{\text{H}}$ indicates C501-1E

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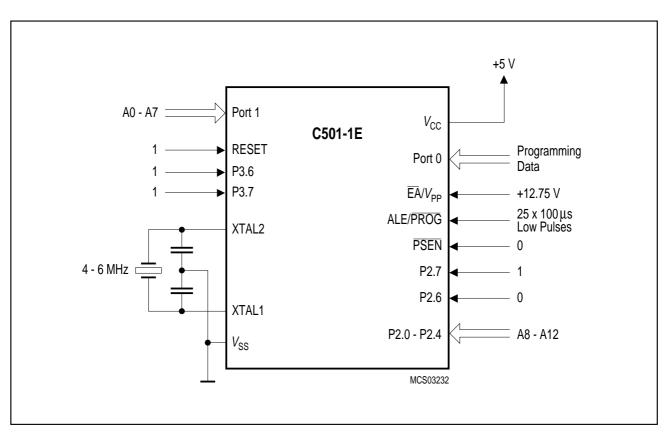


Figure 10 C501-1E OTP Memory Programming Configuration

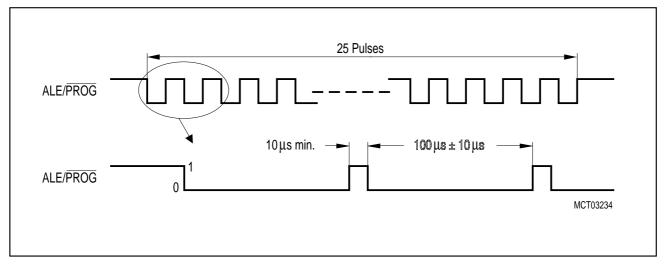


Figure 11 C501-1E ALE/PROG Waveform

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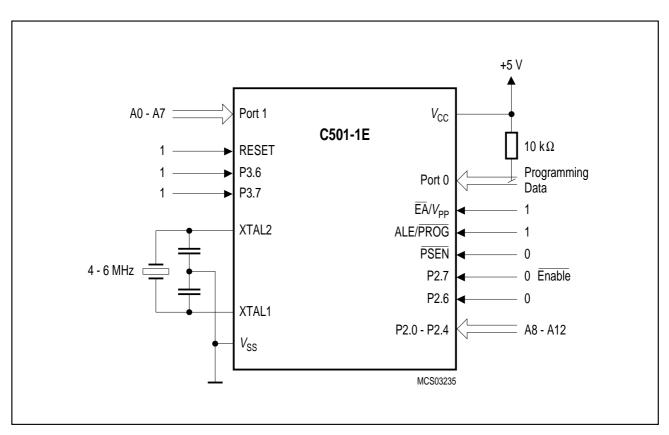


Figure 12 C501-1E OTP Memory Verification

Absolute Maximum Ratings

Ambient temperature under bias (T_A)	– 40 to 85 °C
Storage temperature (T_{stg})	– 65 °C to 150 °C
Voltage on V_{cc} pins with respect to ground (V_{ss})	– 0.5 V to 6.5 V
Voltage on any pin with respect to ground (V_{SS})	– 0.5 V to $V_{\rm CC}$ +0.5 V
Input current on any pin during overload condition	- 10 mA to 10 mA
Absolute sum of all input currents during overload condition	l 100 mA l
Power dissipation	TBD

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage of the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for longer periods may affect device reliability. During overload conditions ($V_{IN} > V_{CC}$ or $V_{IN} < V_{SS}$) the Voltage on V_{CC} pins with respect to ground (V_{SS}) must not exceed the values defined by the absolute maximum ratings.

DC Characteristics for C501-L / C501-1R

 $V_{CC} = 5 \text{ V} + 10 \text{ }\%, -15 \text{ }\%; V_{SS} = 0 \text{ V};$ $T_A = 0 \text{ }^{\circ}\text{C} \text{ to } 70 \text{ }^{\circ}\text{C}$ for the SAB-C501 $T_A = -40 \text{ }^{\circ}\text{C} \text{ to } 85 \text{ }^{\circ}\text{C}$ for the SAF-C501

Parameter	Symbol	Limit	Values	Unit	Test Condition	
		min.	max.	1		
Input low voltage (except \overline{EA} , RESET)	V_{IL}	- 0.5	0.2 V _{cc} – 0.1	V	-	
Input low voltage (EA)	$V_{\rm IL\ 1}$	- 0.5	$0.2 V_{\rm CC} - 0.3$	V	_	
Input low voltage (RESET)	$V_{\rm IL2}$	- 0.5	0.2 V _{cc} + 0.1	V	-	
nput high voltage (except XTAL1, EA, RESET)	V_{IH}	$0.2 V_{\rm CC} + 0.9$	V _{cc} + 0.5	V	-	
nput high voltage to XTAL1	V _{IH 1}	0.7 V _{cc}	V _{CC} + 0.5	V		
nput high voltage to \overline{EA} , RESET	V _{IH 2}	0.6 V _{CC}	V _{cc} + 0.5	V	-	
Dutput low voltage ports 1, 2, 3)	V _{OL}	-	0.45	V	$I_{\rm OL}$ = 1.6 mA ¹⁾	
Dutput low voltage port 0, ALE, <u>PSEN</u>)	V _{OL 1}	-	0.45	V	$I_{\rm OL}$ = 3.2 mA ¹⁾	
Dutput high voltage ports 1, 2, 3)	V _{OH}	2.4 0.9 V _{cc}	-	V	I _{OH} = - 80 μA, I _{OH} = - 10 μA	
Output high voltage (port 0 in external bus mode, ALE, <u>PSEN</u>)	V _{OH 1}	2.4 0.9 V _{cc}	-	V	$I_{\rm OH}$ = - 800 µA ² , $I_{\rm OH}$ = - 80 µA ²	
_ogic 0 input current (ports 1, 2, 3)	I _{IL}	- 10	- 50	μA	V _{IN} = 0.45 V	
_ogical 1-to-0 transition current (ports 1, 2, 3)	I _{TL}	- 65	- 650	μA	$V_{\rm IN} = 2 \rm V$	
nput leakage current (port 0, EA)	I	-	± 1	μA	$0.45 < V_{\rm IN} < V_{\rm CC}$	
Pin capacitance	C _{IO}	-	10	pF	$f_{\rm C}$ = 1 MHz, $T_{\rm A}$ = 25 °C	
Power supply current: Active mode, 12 MHz ⁷⁾ Idle mode, 12 MHz ⁷⁾ Active mode, 24 MHz ⁷⁾ Idle mode, 24 MHz ⁷⁾ Active mode, 40 MHz ⁷⁾ Idle mode, 40 MHz ⁷⁾ Power Down Mode	I_{CC} I_{CC} I_{CC} I_{CC} I_{CC} I_{CC} I_{CC} I_{PD}	- - - -	21 4.8 36.2 8.2 56.5 12.7 50	mA mA mA mA mA mA μA	$V_{CC} = 5 V, {}^{4)}$ $V_{CC} = 5 V, {}^{5)}$ $V_{CC} = 5 V, {}^{4)}$ $V_{CC} = 5 V, {}^{5)}$ $V_{CC} = 5 V, {}^{5)}$ $V_{CC} = 5 V, {}^{5)}$ $V_{CC} = 2 \dots 5.5 V {}^{3)}$	

Notes see page 32.

DC Characteristics for C501-1E

 $V_{\rm CC}$ = 5 V + 10 %, - 15 %; $V_{\rm SS}$ = 0 V;

 $T_{A} = 0 \degree C$ to 70 $\degree C$ for the SAB-C501 $T_{A} = -40 \degree C$ to 85 $\degree C$ for the SAF-C501

Parameter	Symbol	Limit	Values	Unit	Test Condition	
		min.	max.			
Input low voltage (except EA/V _{PP} , RESET)	V_{IL}	- 0.5	0.2 V _{cc} – 0.1	V	-	
Input low voltage (EA/V _{PP})	V _{IL 1}	- 0.5	$0.1 V_{\rm CC} - 0.1$	V	-	
Input low voltage (RESET)	$V_{\rm IL2}$	- 0.5	0.2 V _{cc} + 0.1	V	-	
Input high voltage (except XTAL1, EA/V _{PP} , RESET)	V_{IH}	$0.2 V_{\rm CC} + 0.9$	V _{cc} + 0.5	V	_	
Input high voltage to XTAL1	V _{IH 1}	0.7 V _{cc}	V _{cc} + 0.5	V		
Input high voltage to \overline{EA}/V_{PP} , RESET	V_{IH2}	0.6 V _{cc}	V _{cc} + 0.5	V	-	
Output low voltage (ports 1, 2, 3)	V _{OL}	_	0.45	V	$I_{\rm OL}$ = 1.6 mA ¹⁾	
Output low voltage (port 0, ALE/PROG, PSEN)	V _{OL 1}	_	0.45	V	$I_{\rm OL}$ = 3.2 mA ¹⁾	
Output high voltage (ports 1, 2, 3)	V _{OH}	2.4 0.9 V _{CC}	-	V	I _{OH} = − 80 μA, I _{OH} = − 10 μA	
Output high voltage (port 0 in external bus mode, ALE/PROG, PSEN)	V _{OH 1}	2.4 0.9 V _{cc}	-	V	$I_{\rm OH} = -800 \ \mu {\rm A}^{2},$ $I_{\rm OH} = -80 \ \mu {\rm A}^{2}$	
Logic 0 input current (ports 1, 2, 3)	I _{IL}	- 10	- 50	μA	$V_{\rm IN}$ = 0.45 V	
Logical 1-to-0 transition current (ports 1, 2, 3)	I _{TL}	- 65	- 650	μA	$V_{\rm IN} = 2 \rm V$	
Input leakage current (port 0, EA/V _{PP})	I	-	± 1	μA	$0.45 < V_{\rm IN} < V_{\rm CC}$	
Pin capacitance	C _{IO}	_	10	pF	$f_{\rm C}$ = 1 MHz, $T_{\rm A}$ = 25 °C	
Power supply current: Active mode, 12 MHz ⁷⁾ Idle mode, 12 MHz ⁷⁾ Active mode, 24 MHz ⁷⁾ Idle mode, 24 MHz ⁷⁾ Power Down Mode	$I_{\rm CC}$ $I_{\rm CC}$ $I_{\rm CC}$ $I_{\rm CC}$ $I_{\rm PD}$	- - - -	21 18 36.2 20 50	mA mA mA mA μA	$V_{CC} = 5 V, {}^{4)}$ $V_{CC} = 5 V, {}^{5)}$ $V_{CC} = 5 V, {}^{4)}$ $V_{CC} = 5 V, {}^{5)}$ $V_{CC} = 2 \dots 5.5 V {}^{3)}$	

Notes see next page.

Notes:

- ¹⁾ Capacitive loading on ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL} of ALE and port 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operation. In the worst case (capacitive loading > 100 pF), the noise pulse on ALE line may exceed 0.8 V. In such cases it may be desirable to qualify ALE with a schmitt-trigger, or use an address latch with a schmitt-trigger strobe input.
- ²⁾ Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and \overline{PSEN} to momentarily fall bellow the 0.9 V_{CC} specification when the address lines are stabilizing.
- ³⁾ I_{PD} (Power Down Mode) is measured under following conditions: EA = Port0 = V_{CC} ; RESET = V_{SS} ; XTAL2 = N.C.; XTAL1 = V_{SS} ; all other pins are disconnected.
- ⁴⁾ I_{CC} (active mode) is measured with: XTAL1 driven with t_{CLCH} , $t_{CHCL} = 5$ ns, $V_{IL} = V_{SS} + 0.5$ V, $V_{IH} = V_{CC} - 0.5$ V; XTAL2 = N.C.; $\overline{EA} = Port0 = RESET = V_{CC}$; all other pins are disconnected. I_{CC} would be slightly higher if a crystal oscillator is used (appr. 1 mA).
- ⁵⁾ I_{CC} (Idle mode) is measured with all output pins disconnected and with all peripherals disabled; XTAL1 driven with t_{CLCH} , $t_{CHCL} = 5$ ns, $V_{IL} = V_{SS} + 0.5$ V, $V_{IH} = V_{CC} - 0.5$ V; XTAL2 = N.C.; RESET = $\overline{EA} = V_{SS}$; Port0 = V_{CC} ; all other pins are disconnected;
- ⁷⁾ $I_{CC max}$ at other frequencies is given by: active mode: $I_{CC} = 1.27 \times f_{OSC} + 5.73$ idle mode: $I_{CC} = 0.28 \times f_{OSC} + 1.45$ (C501-L and C501-1R only) where f_{OSC} is the oscillator frequency in MHz. I_{CC} values are given in mA and measured at $V_{CC} = 5 \text{ V}$.

AC Characteristics for C501-L / C501-1R / C501-1E

 $V_{\rm CC} = 5 \text{ V} + 10 \text{ }\%, -15 \text{ }\%; V_{\rm SS} = 0 \text{ V}$ $T_{\rm A} = 0 \text{ }^{\circ}\text{C} \text{ to } 70 \text{ }^{\circ}\text{C}$ for the SAB-C501 $T_{\rm A} = -40 \text{ }^{\circ}\text{C} \text{ to } 85 \text{ }^{\circ}\text{C}$ for the SAF-C501

(C_{L} for port 0, ALE and \overline{PSEN} outputs = 100 pF; C_{L} for all other outputs = 80 pF)

Program Memory Characteristics

Parameter	Symbol	Limit Values				
		12 MHz Clock		Varial 1/t _{cLCL} = 3.5	-	
		min.	max.	min.	max.	
ALE pulse width	t _{LHLL}	127	-	$2t_{CLCL} - 40$	-	ns
Address setup to ALE	t _{AVLL}	43	-	$t_{\rm CLCL} - 40$	-	ns
Address hold after ALE	t _{LLAX}	30	-	<i>t</i> _{CLCL} – 53	-	ns
ALE low to valid instr in	t _{LLIV}	-	233	_	$4t_{CLCL} - 100$	ns
ALE to PSEN	t _{LLPL}	58	-	$t_{\rm CLCL} - 25$	-	ns
PSEN pulse width	t _{PLPH}	215	-	$3t_{CLCL} - 35$	-	ns
PSEN to valid instr in	t _{PLIV}	-	150	-	$3t_{CLCL} - 100$	ns
Input instruction hold after PSEN	t _{PXIX}	0	-	0	-	ns
Input instruction float after PSEN	$t_{PXIZ}^{*)}$	-	63	-	$t_{\rm CLCL} - 20$	ns
Address valid after PSEN	t _{PXAV} *)	75	-	$t_{\rm CLCL} - 8$	-	ns
Address to valid instr in	<i>t</i> _{AVIV}	-	302	-	5 <i>t</i> _{CLCL} – 115	ns
Address float to PSEN	t _{AZPL}	0	-	0	-	ns

*) Interfacing the C501 to devices with float times up to 75 ns is permissible. This limited bus contention will not cause any damage to port 0 Drivers.

AC Characteristics for C501-L / C501-1R / C501-1E (cont'd)

External Data Memory Characteristics

Parameter	Symbol	Limit Values				
		12 MHz Clock		Variab 1/t _{cLCL} = 3.5 I	-	
		min.	max.	min.	max.	
RD pulse width	t _{RLRH}	400	_	$6t_{CLCL} - 100$	-	ns
WR pulse width	t _{wLWH}	400	_	$6t_{CLCL} - 100$	-	ns
Address hold after ALE	t _{LLAX2}	30	_	$t_{\rm CLCL} - 53$	-	ns
RD to valid data in	t _{RLDV}	-	252	-	5 <i>t</i> _{CLCL} – 165	ns
Data hold after RD	t _{RHDX}	0	_	0	-	ns
Data float after RD	t _{RHDZ}	_	97	-	$2t_{\text{CLCL}} - 70$	ns
ALE to valid data in	t _{LLDV}	-	517	-	8 <i>t</i> _{CLCL} – 150	ns
Address to valid data in	<i>t</i> _{AVDV}	-	585	-	9 <i>t</i> _{CLCL} – 165	ns
ALE to \overline{WR} or \overline{RD}	t _{LLWL}	200	300	$3t_{\text{CLCL}} - 50$	$3t_{CLCL} + 50$	ns
Address valid to \overline{WR} or \overline{RD}	<i>t</i> _{AVWL}	203	_	$4t_{CLCL} - 130$	-	ns
$\overline{\text{WR}}$ or $\overline{\text{RD}}$ high to ALE high	t _{WHLH}	43	123	$t_{\rm CLCL} - 40$	<i>t</i> _{CLCL} + 40	ns
Data valid to WR transition	t _{QVWX}	33	_	$t_{\rm CLCL} - 50$	-	ns
Data setup before WR	t _{QVWH}	433	_	7 <i>t</i> _{CLCL} – 150	-	ns
Data hold after WR	t _{WHQX}	33	_	$t_{\rm CLCL} - 50$	-	ns
Address float after RD	t _{RLAZ}	-	0	-	0	ns

External Clock Drive Characteristics

Parameter	Symbol		Unit	
		Freq		
		min.	max.	
Oscillator period	t _{CLCL}	83.3	285.7	ns
High time	t _{chcx}	20	$t_{\rm CLCL} - t_{\rm CLCX}$	ns
Low time	t _{CLCX}	20	$t_{\rm CLCL} - t_{\rm CHCX}$	ns
Rise time	t _{CLCH}	-	20	ns
Fall time	t _{CHCL}	-	20	ns

AC Characteristics for C501-L24 / C501-1R24 / C501-1E24

 $V_{CC} = 5 \text{ V} + 10 \text{ }\%, -15 \text{ }\%; V_{SS} = 0 \text{ V}$ $T_A = 0 \text{ }^{\circ}\text{C} \text{ to } 70 \text{ }^{\circ}\text{C}$ for the SAB-C501 $T_A = -40 \text{ }^{\circ}\text{C} \text{ to } 85 \text{ }^{\circ}\text{C}$ for the SAF-C501

(C_{L} for port 0, ALE and \overline{PSEN} outputs = 100 pF; C_{L} for all other outputs = 80 pF)

Program Memory Characteristics

Parameter	Symbol	Limit Values				Unit
		24 MHz Clock		Variable Clock 1/t _{CLCL} = 3.5 MHz to 24 MHz		
		min.	max.	min.	max.	1
ALE pulse width	t _{LHLL}	43	-	$2t_{CLCL} - 40$	-	ns
Address setup to ALE	t _{AVLL}	17	-	<i>t</i> _{CLCL} – 25	-	ns
Address hold after ALE	t _{LLAX}	17	-	t _{CLCL} – 25	-	ns
ALE low to valid instr in	t _{LLIV}	-	80	_	$4t_{CLCL} - 87$	ns
ALE to PSEN	t _{LLPL}	22	-	$t_{\rm CLCL} - 20$	-	ns
PSEN pulse width	t _{PLPH}	95	-	$3t_{CLCL} - 30$	-	ns
PSEN to valid instr in	t _{PLIV}	-	60	_	$3t_{\text{CLCL}} - 65$	ns
Input instruction hold after PSEN	t _{PXIX}	0	-	0	-	ns
Input instruction float after PSEN	$t_{PXIZ}^{*)}$	-	32	-	$t_{\rm CLCL} - 10$	ns
Address valid after PSEN	t _{PXAV} *)	37	-	$t_{\rm CLCL} - 5$	-	ns
Address to valid instr in	<i>t</i> _{AVIV}	-	148	-	$5t_{\text{CLCL}} - 60$	ns
Address float to PSEN	t _{AZPL}	0	-	0	-	ns

*) Interfacing the C501 to devices with float times up to 37 ns is permissible. This limited bus contention will not cause any damage to port 0 Drivers.

AC Characteristics for C501-L24 / C501-1R24 / C501-1E24 (cont'd)

External Data Memory Characteristics

Parameter	Symbol	Limit Values				Unit
		24 MHz Clock		Variable Clock 1/t _{CLCL} = 3.5 MHz to 24 MHz		-
		min.	max.	min.	max.]
RD pulse width	t _{RLRH}	180	-	$6t_{CLCL} - 70$	-	ns
WR pulse width	t _{wLWH}	180	-	$6t_{CLCL} - 70$	-	ns
Address hold after ALE	t _{LLAX2}	15	_	$t_{\rm CLCL} - 27$	-	ns
RD to valid data in	t _{RLDV}	_	118	-	5 <i>t</i> _{CLCL} – 90	ns
Data hold after RD	t _{RHDX}	0	-	0	-	ns
Data float after RD	t _{RHDZ}	_	63	-	$2t_{\text{CLCL}} - 20$	ns
ALE to valid data in	t _{LLDV}	_	200	-	8 <i>t</i> _{CLCL} – 133	ns
Address to valid data in	t _{AVDV}	-	220	-	9 <i>t</i> _{CLCL} – 155	ns
ALE to \overline{WR} or \overline{RD}	t _{LLWL}	75	175	$3t_{CLCL} - 50$	$3t_{CLCL}$ + 50	ns
Address valid to \overline{WR} or \overline{RD}	t _{AVWL}	67	-	4 <i>t</i> _{CLCL} - 97	-	ns
$\overline{\text{WR}}$ or $\overline{\text{RD}}$ high to ALE high	t _{WHLH}	17	67	<i>t</i> _{CLCL} – 25	<i>t</i> _{CLCL} + 25	ns
Data valid to WR transition	t _{QVWX}	5	-	t _{CLCL} – 37	-	ns
Data setup before WR	t _{QVWH}	170	-	7 <i>t</i> _{CLCL} – 122	-	ns
Data hold after WR	t _{WHQX}	15	-	t _{CLCL} – 27	-	ns
Address float after RD	t _{RLAZ}	-	0	-	0	ns

External Clock Drive Characteristics

Parameter	Symbol		Unit	
		Freq		
		min.	max.	
Oscillator period	t _{CLCL}	41.7	285.7	ns
High time	t _{CHCX}	12	$t_{\rm CLCL} - t_{\rm CLCX}$	ns
Low time	t _{CLCX}	12	$t_{\rm CLCL} - t_{\rm CHCX}$	ns
Rise time	t _{CLCH}	-	12	ns
Fall time	t _{CHCL}	-	12	ns

AC Characteristics for C501-L40 / C501-1R40

 $V_{CC} = 5 \text{ V} + 10 \text{ }\%, -15 \text{ }\%; V_{SS} = 0 \text{ V}$ $T_A = 0 \text{ }^{\circ}\text{C} \text{ to } 70 \text{ }^{\circ}\text{C}$ for the SAB-C501 $T_A = -40 \text{ }^{\circ}\text{C} \text{ to } 85 \text{ }^{\circ}\text{C}$ for the SAF-C501

(C_{L} for port 0, ALE and \overline{PSEN} outputs = 100 pF; C_{L} for all other outputs = 80 pF)

Program Memory Characteristics

Parameter	Symbol	Limit Values				Unit
		40 MHz Clock		Variable Clock $1/t_{CLCL} = 3.5$ MHz to 40 MHz		
		min.	max.	min.	max.	
ALE pulse width	t _{LHLL}	35	-	2 <i>t</i> _{CLCL} – 15	-	ns
Address setup to ALE	t _{AVLL}	10	-	<i>t</i> _{CLCL} – 15	-	ns
Address hold after ALE	t _{LLAX}	10	-	<i>t</i> _{CLCL} – 15	-	ns
ALE low to valid instr in	t _{LLIV}	-	55	-	4 <i>t</i> _{CLCL} – 45	ns
ALE to PSEN	t _{LLPL}	10	-	<i>t</i> _{CLCL} – 15	-	ns
PSEN pulse width	t _{PLPH}	60	-	3 t _{CLCL} – 15	_	ns
PSEN to valid instr in	t _{PLIV}	-	25	-	3 <i>t</i> _{CLCL} – 50	ns
Input instruction hold after PSEN	t _{PXIX}	0	_	0	-	ns
Input instruction float after PSEN	$t_{PXIZ}^{*)}$	-	20	_	$t_{\rm CLCL}$ – 5	ns
Address valid after PSEN	t _{PXAV} *)	20	_	$t_{\rm CLCL}$ – 5	-	ns
Address to valid instr in	<i>t</i> _{AVIV}	-	65	-	5 <i>t</i> _{CLCL} – 60	ns
Address float to PSEN	t _{AZPL}	- 5	-	- 5	-	ns

*) Interfacing the C501 to devices with float times up to 25ns is permissible. This limited bus contention will not cause any damage to port 0 Drivers.

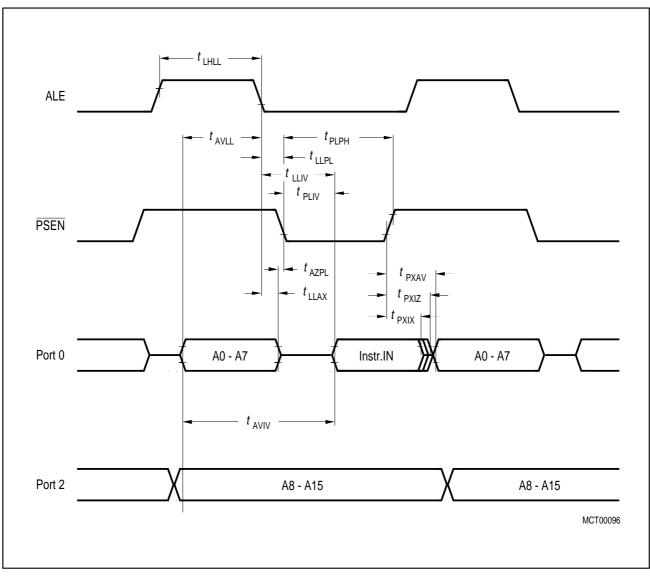
AC Characteristics for C501-L40 / C501-1R40 (cont'd)

External Data Memory Characteristics

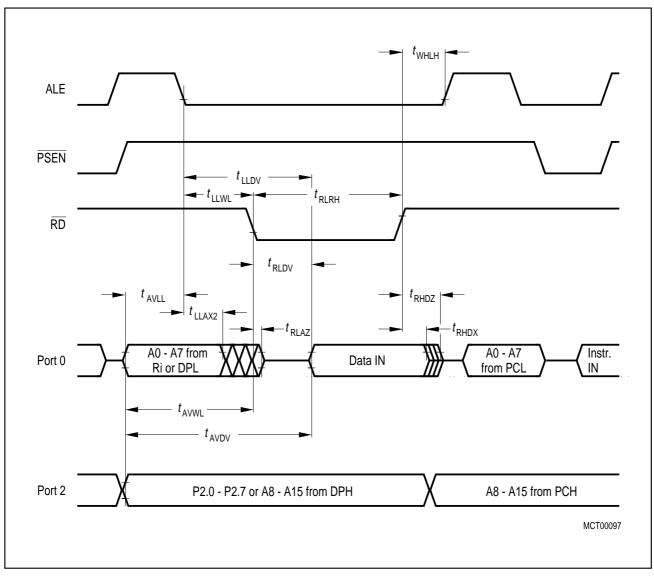
Parameter	Symbol	Limit Values				Unit
		40 MHz Clock		Variable Clock 1/t _{CLCL} = 3.5 MHz to 40 MHz		-
		min.	max.	min.	max.	1
RD pulse width	t _{RLRH}	120	-	6 <i>t</i> _{CLCL} – 30	_	ns
WR pulse width	t _{wLwH}	120	-	6 <i>t</i> _{CLCL} – 30	-	ns
Address hold after ALE	t _{LLAX2}	10	-	<i>t</i> _{CLCL} – 15	-	ns
RD to valid data in	t _{RLDV}	-	75	-	5 t _{CLCL} - 50	ns
Data hold after RD	t _{RHDX}	0	-	0	-	ns
Data float after RD	t _{RHDZ}	-	38	-	2 <i>t</i> _{CLCL} – 12	ns
ALE to valid data in	t _{LLDV}	-	150	-	8 t _{CLCL} - 50	ns
Address to valid data in	<i>t</i> _{AVDV}	-	150	-	9 <i>t</i> _{CLCL} - 75	ns
ALE to \overline{WR} or \overline{RD}	t _{LLWL}	60	90	3 <i>t</i> _{CLCL} – 15	3 <i>t</i> _{CLCL} + 15	ns
Address valid to \overline{WR} or \overline{RD}	<i>t</i> _{AVWL}	70	_	4 <i>t</i> _{CLCL} – 30	-	ns
$\overline{\text{WR}}$ or $\overline{\text{RD}}$ high to ALE high	t _{WHLH}	10	40	<i>t</i> _{CLCL} – 15	<i>t</i> _{CLCL} + 15	ns
Data valid to WR transition	t _{QVWX}	5	-	<i>t</i> _{CLCL} – 20	-	ns
Data setup before WR	t _{QVWH}	125	-	7 <i>t</i> _{CLCL} – 50	-	ns
Data hold after WR	t _{WHQX}	5	_	<i>t</i> _{CLCL} – 20	-	ns
Address float after RD	t _{RLAZ}	-	0	-	0	ns

External Clock Drive Characteristics

Parameter	Symbol		Unit	
		Freq		
		min.	max.	
Oscillator period	t _{CLCL}	25	285.7	ns
High time	t _{CHCX}	10	$t_{\rm CLCL} - t_{\rm CLCX}$	ns
Low time	t _{CLCX}	10	$t_{\rm CLCL} - t_{\rm CHCX}$	ns
Rise time	t _{CLCH}	-	10	ns
Fall time	t _{CHCL}	-	10	ns









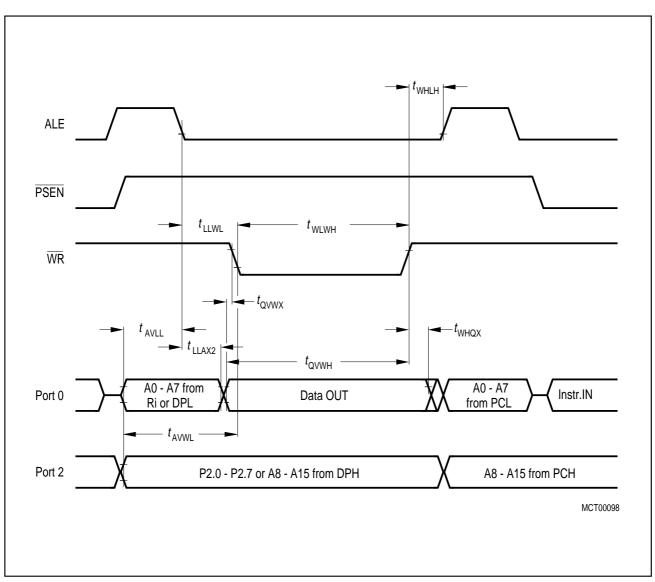


Figure 15 Data Memory Write Cycle

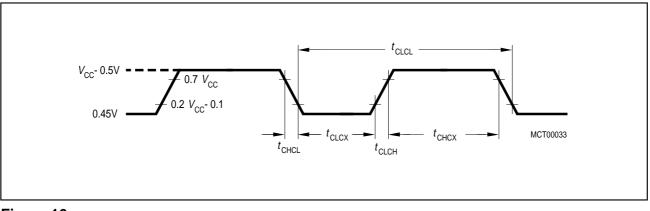


Figure 16 External Clock Drive at XTAL2

ROM Verification Characteristics for C501-1R

ROM Verification Mode 1

Parameter	Symbol		Unit	
		min.	max.	
Address to valid data	<i>t</i> _{AVQV}	_	48t _{CLCL}	ns
ENABLE to valid data	t _{ELQV}	-	48t _{CLCL}	ns
Data float after ENABLE	t _{EHQZ}	0	48t _{CLCL}	ns
Oscillator frequency	1/t _{CLCL}	4	6	MHz

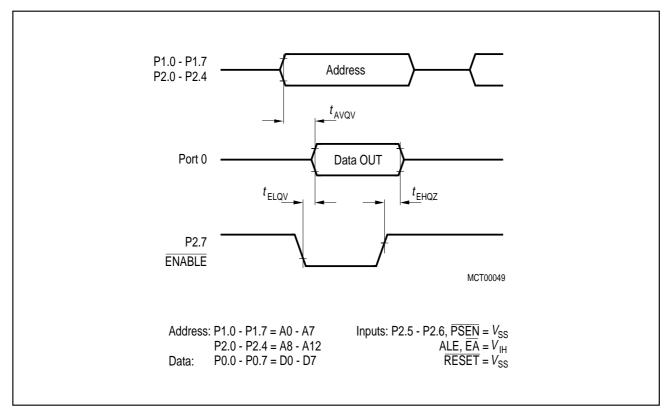


Figure 17 ROM Verification Mode 1

OTP Programming and Verification Characteristics

 $V_{\rm CC}$ = 5 V ± 10%, $V_{\rm SS}$ = 0 V, $T_{\rm A}$ = 21 °C to + 27 °C

Parameter	Symbol	Limit Values		Unit
		min.	max.	
Programming supply voltage	V _{PP}	12.5	13.0	V
Programming supply current	I _{PP}	-	50	mA
Oscillator frequency	1 / <i>t</i> _{CLCL}	4	6	MHz
Address setup to ALE/PROG low	<i>t</i> _{AVGL}	48 t _{CLCL}	-	ns
Address hold after ALE/PROG	t _{GHAX}	48 t _{CLCL}	-	ns
Data setup to ALE/PROG low	t _{DVGL}	48 t _{CLCL}	-	ns
Data hold after ALE/PROG	t _{GHDX}	48 t _{CLCL}	-	ns
P2.7 (ENABLE) high to V _{PP}	t _{EHSH}	48 t _{CLCL}	-	ns
V _{PP} setup to ALE/PROG low	t _{SHGL}	10	-	μs
V _{PP} hold after ALE/PROG low	t _{GHSL}	10	-	μs
ALE/PROG width	t _{GLGH}	90	110	μs
Address to data valid	<i>t</i> _{AVQV}	-	48 t _{CLCL}	ns
ENABLE low to data valid	t _{ELQV}	-	48 t _{CLCL}	ns
Data float after ENABLE	t _{EHQZ}	0	48 t _{CLCL}	ns
ALE/PROG high to ALE/PROG low	t _{GHGL}	10	_	μs

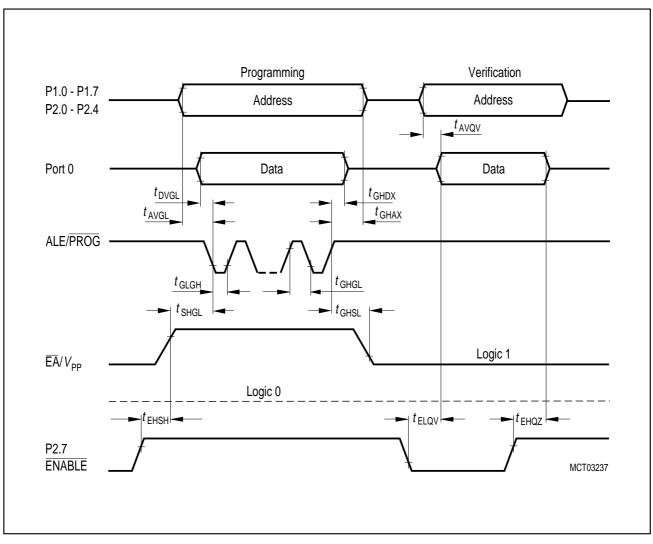


Figure 18 C501-1E OTP Memory Program/Read Cycle

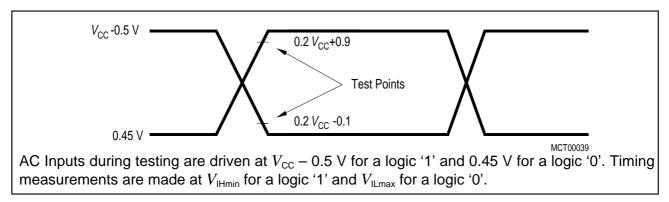


Figure 19 AC Testing: Input, Output Waveforms

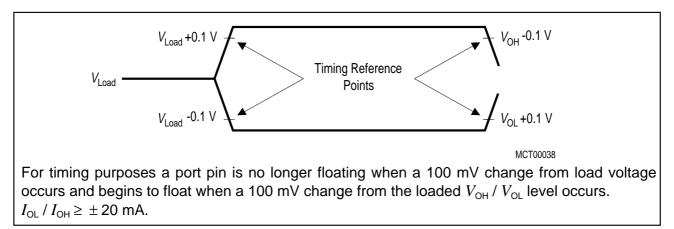


Figure 20 AC Testing: Float Waveforms

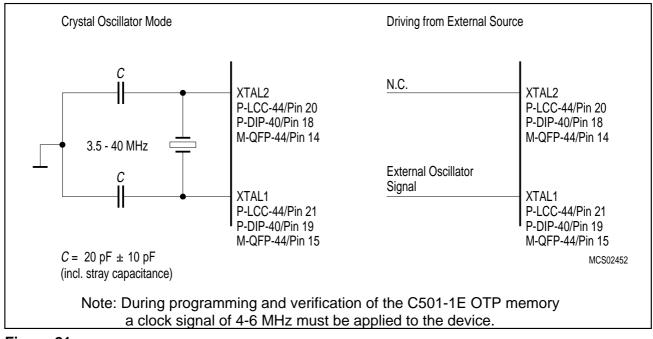
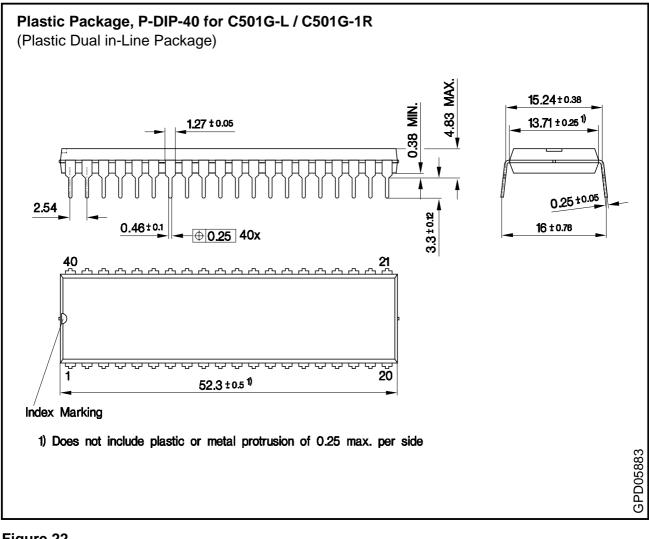


Figure 21 Recommended Oscillator Circuits

Package Outlines

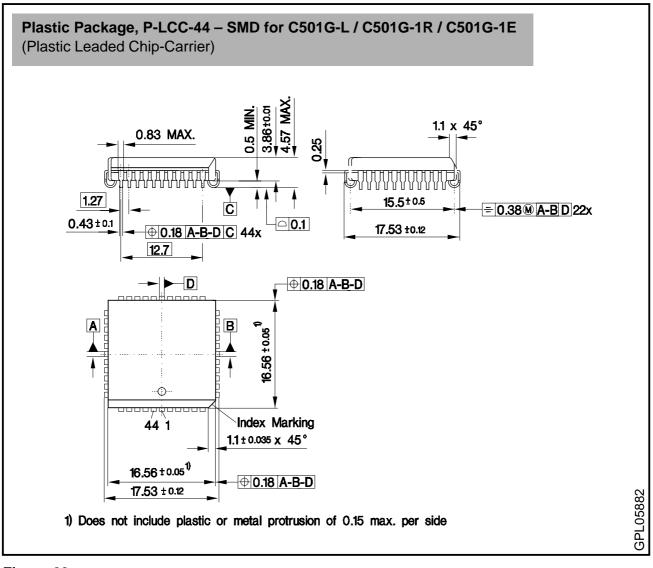




Sorts of Packing

Package outlines for tubes, trays etc. are contained in our Data Book "Package Information"

Dimensions in mm





Sorts of Packing Package outlines for tubes, trays etc. are contained in our Data Book "Package Information" SMD = Surface Mounted Device

Dimensions in mm

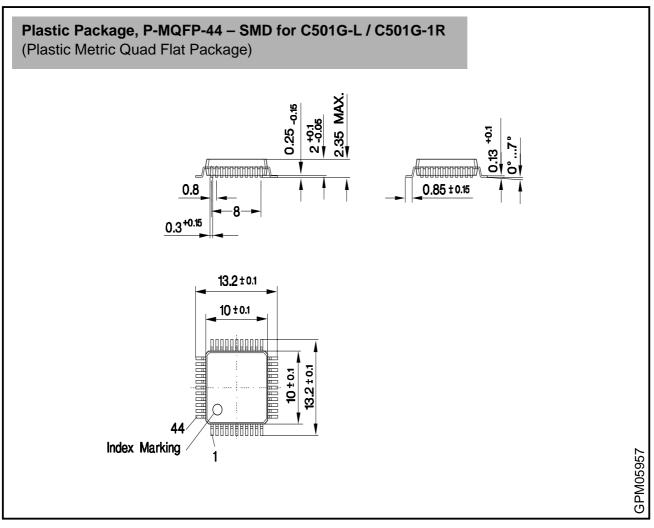


Figure 24 P-MQFP-44 Package Outlines

Sorts of Packing Package outlines for tubes, trays etc. are contained in our Data Book "Package Information" SMD = Surface Mounted Device

Dimensions in mm